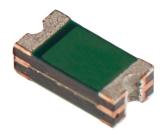


RoHS Compliant



Applications

All high density boards.

Features

- · Small Surface Mountable
- Solid State
- · Faster Time to Trip
- Lower Resistance
- Operation Current: 0.05A to 2A
- · Maximum Voltage: 6V to 60V DC
- -40°C to +85°C Temperature Range
- Halogen Free

Electrical Characteristics (23°C)

Part Number	Hold Current	Trip Current	Rated Voltage	Max. Current	Typical Power	Max. Time to Trip		Resistance	
Part Number	Iн (A)	Iт (A)	V _{MAX} (V DC)	Імах. (А)	Pd (W)	Current (A)	Time (Sec)	R _{MIN} . (Ω)	R1 _{MAX} . (Ω)
MC011406	0.05	0.15	60	100	0.4	0.25	1.5	3.6	50
MC011407	0.1	0.25	60	100	0.4	0.5	1	1.6	15
MC011408	0.12	0.39	48	100	0.5	1	0.2	1.4	6.5
MC011409	0.16	0.45	48	100	0.5	1	0.3	1.1	5
MC011410	0.25	0.5	16	100	0.6	8	0.08	0.55	2.3
MC011411	0.25	0.5	24	100	0.6	8	0.08	0.55	2.3
MC011412	0.35	0.75	30	100	0.6	8	0.1	0.3	1.2
MC011413	0.5	1	24	100	0.6	8	0.1	0.15	0.75
MC011414	0.75	1.5	16	100	0.6	8	0.2	0.09	0.29
MC011415	1.1	2.2	16	100	0.8	8	0.3	0.04	0.18
MC011416	2	3.5	6	100	0.8	8	1.5	0.018	0.08

Ін = Hold current-maximum current at which the device will not trip at 23°C still air.

RMIN = Minimum device resistance at 23°C prior to tripping.

R1MAX = Maximum device resistance at 23°C measured 1 hour after tripping or reflow soldering of 260°C for 20 seconds.

Termination pad materials: Pure Tin



Iτ = Trip current-minimum current at which the device will always trip at 23°C still air.

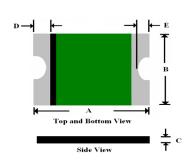
VMAX = Maximum voltage device can withstand without damage at it rated current.(IMAX.)

IMAX = Maximum fault current device can withstand without damage at rated voltage. (VMAX.)

Pd = Typical power dissipated-type amount of power dissipated by the device when in the tripped state in 23°C still air environment.



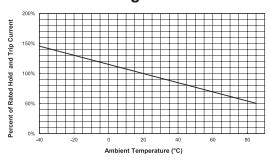
Dimensions



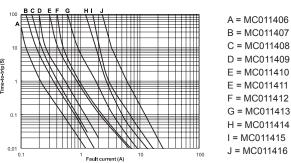
Part Number	Α		В		С		D		E	
Part Number	Min.	Max.								
MC011406	3	3.5	1.5	1.8	0.45	0.85	0.1	0.75	0.1	0.45
MC011407	3	3.5	1.5	1.8	0.45	0.85	0.1	0.75	0.1	0.45
MC011408	3	3.5	1.5	1.8	0.45	0.85	0.1	0.75	0.1	0.45
MC011409	3	3.5	1.5	1.8	0.45	0.75	0.1	0.75	0.1	0.45
MC011410	3	3.5	1.5	1.8	0.45	0.75	0.1	0.75	0.1	0.45
MC011411	3	3.5	1.5	1.8	0.45	0.75	0.1	0.75	0.1	0.45
MC011412	3	3.5	1.5	1.8	0.9	1.3	0.25	0.75	0.1	0.45
MC011413	3	3.5	1.5	1.8	0.8	1.2	0.25	0.75	0.1	0.45
MC011414	3	3.5	1.5	1.8	0.45	1.25	0.25	0.75	0.1	0.45
MC011415	3	3.5	1.5	1.8	0.8	1.4	0.25	0.75	0.1	0.45
MC011416	3	3.5	1.5	1.8	0.85	1.6	0.25	0.75	0.1	0.45

Dimensions: Millimetres

Thermal Derating Curve



Typical Time-To-Trip at 23°C

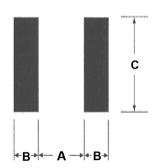


Material Specifications

- · Terminal Pad Material: Pure Tin
- Soldering Characteristics: Meets EIA specifications RS 186-9E, ANSI/J-std-002 Category 3

Pad Layouts - Solder Reflow and Rework Recommendations

The dimension in the table below provide the recommended pad layout.



Pad Dimensions

A	B	C		
Nominal	Nominal	Nominal		
2mm	1mm	1.9mm		





Profile Feature	Pb-Free Assembly			
Average Ramp-Up Rate (Tsmax to Tp)	3°C / second max.			
Preheat: Temperature Min (Tsmin) Temperature Max (Tsmax) Time (tsmin to tsmax)	150°C 200°C 60 - 180 seconds			
Time Maintained Above: Temperature T(L) Time t(L)	217°C 60 - 150 seconds			
Peak/Classification Temperature (Tp):	260°C			
Time within 5°C of Actual Peak: Temperature (tp)	20 - 40 seconds			
Ramp-Down Rate:	6°C / second max.			
Time 25°C to Peak Temperature:	8 minutes max.			

Note: 1. All temperature refers to the package; measured on the package body surface.

Solder Reflow

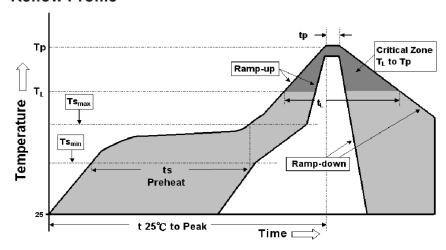
Due to "Lead Free" nature, Temperature and Dwelling time for the soldering zone is higher than those for Regular. This may cause damage to other components.

- 1. Recommended max past thickness > 0.25mm.
- 2. Devices can be cleaned using standard methods and aqueous solvent.
- 3. Rework use standard industry practices.
- 4. Storage Environment: < 30°C / 60%RH

Caution

- 1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- 2. Devices are not designed to be wave soldered to the bottom side of the board.

Reflow Profile







Part Number Table

Description	Part Number		
PTC Resettable Fuse, 0.05A, 60V DC, 1206	MC011406		
PTC Resettable Fuse, 0.1A, 60V DC, 1206	MC011407		
PTC Resettable Fuse, 0.12A, 48V DC, 1206	MC011408		
PTC Resettable Fuse, 0.16A, 48V DC, 1206	MC011409		
PTC Resettable Fuse, 0.25A, 16V DC, 1206	MC011410		
PTC Resettable Fuse, 0.25A, 24V DC, 1206	MC011411		
PTC Resettable Fuse, 0.35A, 30V DC, 1206	MC011412		
PTC Resettable Fuse, 0.5A, 24V DC, 1206	MC011413		
PTC Resettable Fuse, 0.75A, 16V DC, 1206	MC011414		
PTC Resettable Fuse, 1.1A, 16V DC, 1206	MC011415		
PTC Resettable Fuse, 2A, 6V DC, 1206	MC011416		

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